E' concl'd.

a printed circuit board covering the entire first layer and the hollowed out portion and having an opposing surface provided opposite the face of the piezoelectric substrate with the first layer disposed between said opposing surface and said face, said opposing surface having an area equal to an area of said face of said piezoelectric substrate, said printed circuit board further having external conductive contacts; and

conductive via holes going through the first layer and the printed circuit board and connecting the internal and external conductive contacts,

wherein the first layer is in direct contact and completely surrounds each of the conductive via holes and each of the internal conductive contacts.

REMARKS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 1-6 are pending in the present application. Claim 1 has been amended by the present amendment.

In the outstanding Office Action, Claims 1-6 were rejected under 35 U.S.C. § 103(a) as unpatentable in view of Onishi et al ('142), Tsuji et al or Onishi et al ('368) in view of Takoshima, which is respectfully traversed.

Claim 1 is directed to a surface acoustic wave component including a first layer located on a face of a piezoelectric substrate and having a hollowed out portion at least to a level of at least one active surface of the piezoelectric substrate. Further, the piezoelectric substrate has at least two internal conductive contacts disposed on the face of the piezoelectric substrate. The first layer is in direct contact and completely surrounds the internal conductive contacts disposed on the face of the piezoelectric substrate.